

Amendments to the Claims:

1-25. (cancelled)

26. (previously presented): A method of forming an insulated flexible electrical circuit suitable for implantation, comprising the steps of:

choosing a rigid substrate;

cleaning said rigid substrate;

depositing a first polyparaxylylene layer on said rigid substrate;

depositing an electrical conductor on said first polyparaxylylene layer;

patterning said electrical conductor to form a conductive path thereon;

depositing a second polyparaxylylene layer;

defining at least one select portion of said second polyparaxylylene layer;

and

removing said at least one select portion of said second polyparaxylylene layer defining at least one aperture therein, thereby forming at least one electrode that is suitable for contacting living tissue.

27. (previously presented): The method of claim 26, wherein said step of choosing a rigid substrate is accomplished by choosing said substrate comprised of glass.

28. (previously presented): The method of claim 26, further comprising the step of enhancing said first polyparaxylylene layer for adhesion after said step of depositing a first polyparaxylylene layer.

29. (previously presented): The method of claim 26, further comprising the step of enhancing said electrical conductor for adhesion after said step of patterning said electrical conductor to form a conductive path.

30. (previously presented): The method of claim 26, further comprising the step of enhancing said first polyparaxylylene layer for adhesion before said step of depositing a second polyparaxylylene layer.

31. (previously presented): The method of claim 26, further comprising the step of applying silane to enhance adhesion.

32. (previously presented): The method of claim 26, further comprising the step of modifying by chemical means said first polyparaxylylene layer.

33. (previously presented): The method of claim 26, further comprising the step of roughening the polyparaxylylene surface.

34. (previously presented): The method of claim 26, further comprising the step of compressing thermally said first polyparaxylylene layer and said second polyparaxylylene layer to increase adhesion.

35. (previously presented): The method of claim 26, wherein said step of removing said at least one select portion of said second polyparaxylylene layer is accomplished by etching with reactive ions.